Semiconductor Device Type: **NEA-WQFN-16-3x3x0.8mm-NiPdAu**

Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm
Die	Silicon	7440-21-3	4.66	0.98	46582
Lead Frame	Copper	7440-50-8	30.75	6.46	307456
Lead Frame	Iron	7439-89-6	0.73	0.15	7296
Lead Frame	Zinc	7440-66-6	0.05	0.01	480
Lead Frame	Phosphorus	7723-14-0	0.01	0.00	96
Lead Frame	Nickel	7440-02-0	0.44	0.09	4416
Lead Frame	Palladium	7440-05-3	0.02	0.00	192
Lead Frame	Gold	7440-57-5	0.01	0.00	64
Die Attach Material	Silver	7440-22-4	0.06	0.01	624
Die Attach Material	Bisphenol F Type Epoxy Resin	9003-36-5	0.00	0.00	32
Die Attach Material	Epoxy Resin	Trade Secret	0.00	0.00	40
Die Attach Material	Hardener	Trade Secret	0.00	0.00	32
Die Attach Material	Ethylene dimethacrylate	97-90-5	0.00	0.00	40
Die Attach Material	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0	0.00	0.00	16
Die Attach Material	Dicyandiamide	461-58-5	0.00	0.00	8
Die Attach Material	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8	0.00	0.00	8
Bonding Wire	Gold	7440-57-5	0.10	0.02	1000
Molding Compound	Epoxy Resin	Trade secret	3.79	0.80	37897
Molding Compound	Phenol Resin	Trade secret	1.89	0.40	18949
Molding Compound	Silica(Amorphous) A	60676-86-0	50.53	10.61	505295
Molding Compound	Silica(Amorphous) B	7631-86-9	6.32	1.33	63162
Molding Compound	Carbon Black	1333-86-4	0.63	0.13	6316
		TOTALS:	**100.00**	**21.00**	**1,000,000**

21.00 mg Total Mass

		Package Homogeneous Materials		
0.98	**(mg) Total**	**Die**	**% of Total Weight**	**4.66**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
6.72	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**32.00**
	Copper	7440-50-8	96.08	
	Iron	7439-89-6	2.28	
	Zinc	7440-66-6	0.15	
	Phosphorus	7723-14-0	0.03	
	Nickel	7440-02-0	1.38	
	Palladium	7440-05-3	0.06	
	Gold	7440-57-5	0.02	
		Total	**100.00**	
0.02	**(mg) Total**	**Die Attach Material**	**% of Total Weight**	**0.08**
	Silver	7440-22-4	78.00	
	Bisphenol F Type Epoxy Resin	9003-36-5	4.00	
	Epoxy Resin	Trade Secret	5.00	
	Hardener	Trade Secret	4.00	
	Ethylene dimethacrylate	97-90-5	5.00	
	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0	2.00	
	Dicyandiamide	461-58-5	1.00	
	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8	1.00	
		Total	**100.00**	
0.02	**(mg) Total**	**Bonding Wire**	**% of Total Weight**	**0.10**
	Gold	7440-57-5	100.00	
		Total	**100.00**	
13.26	**(mg) Total**	**Molding Compound**	**% of Total Weight**	**63.16**
	Epoxy Resin	Trade secret	6.00	
	Phenol Resin	Trade secret	3.00	
	Silica(Amorphous) A	60676-86-0	80.00	
	Silica(Amorphous) B	7631-86-9	10.00	
	Carbon Black	1333-86-4	1.00	
21.00		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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